

650V N-Channel Mosfet

FEATURES

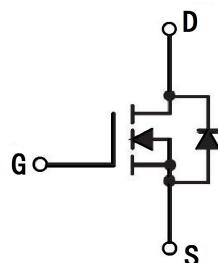
- $R_{DS(ON)} \leq 0.54 \Omega$ (0.46Ω Typ.)
@ $V_{GS}=10V$

TO-220F

1. GATE
2. DRAIN
3. SOURCE

APPLICATIONS

- Load Switch
- PWM Application
- Power management

N-CHANNEL MOSFET**MAXIMUM RATINGS ($T_c=25^\circ C$ unless otherwise noted)**

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		650	V
V_{GSS}	Gate-Source Voltage		± 30	V
I_D	Continuous Drain Current	$T_c = 25^\circ C$	16	A
		$T_c = 100^\circ C$	10	A
I_{DM}	Pulsed Drain Current ^{note1}		64	A
E_{AS}	Single Pulsed Avalanche Energy ^{note2}		470	mJ
P_D	Power Dissipation	$T_c = 25^\circ C$	98	W
R_{eJC}	Thermal Resistance, Junction to Case		1.27	$^\circ C/W$
R_{eJA}	Thermal Resistance, Junction to Ambient		62.5	$^\circ C/W$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	$^\circ C$

MOSFET ELECTRICAL CHARACTERISTICS T_c=25 °C unless otherwise specified

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	650	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 650V, V _{GS} = 0V, T _J = 25°C	-	-	1	μA
I _{SS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±30V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D =250μA	2	3	4	V
R _{D(on)}	Static Drain-Source on-Resistance note3	V _{GS} =10V, I _D =8A	-	0.46	0.54	Ω
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz	-	2200	-	pF
C _{oss}	Output Capacitance		-	213	-	pF
C _{rss}	Reverse Transfer Capacitance		-	13.7	-	pF
Q _g	Total Gate Charge	V _{DD} = 520V, I _D = 8A, V _{GS} = 10V	-	71	-	nC
Q _{gs}	Gate-Source Charge		-	10	-	nC
Q _{gd}	Gate-Drain("Miller") Charge		-	32	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} = 325V, I _D = 8A, R _G = 25Ω	-	35	-	ns
t _r	Turn-on Rise Time		-	50	-	ns
t _{d(off)}	Turn-off Delay Time		-	160	-	ns
t _f	Turn-off Fall Time		-	65	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current	-	-	16	-	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	64	-	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _{SD} =8A	-	-	1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} =0V, I _S =8A, di/dt=100A/μs	-	430	-	ns
Q _{rr}	Reverse Recovery Charge		-	6.5	-	μC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: T_J = 25°C, V_{DD} = 50V, VG=10V, L=10mH, I_{AS} =9.7A

3. Pulse Test: Pulse Width≤300μs, Duty Cycles≤1%

TYPICAL PERFORMANCE CHARACTERISTICS

Figure 1: Output Characteristics

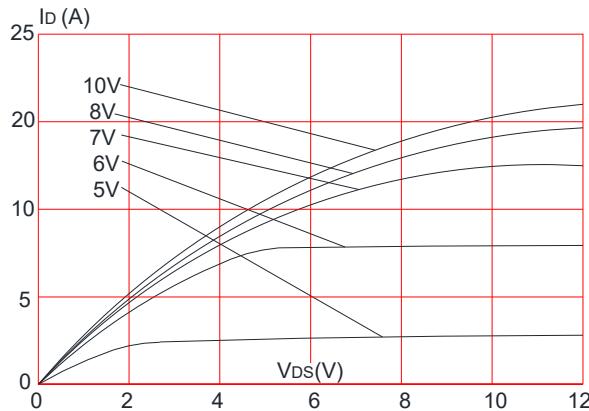


Figure 2: Typical Transfer Characteristics

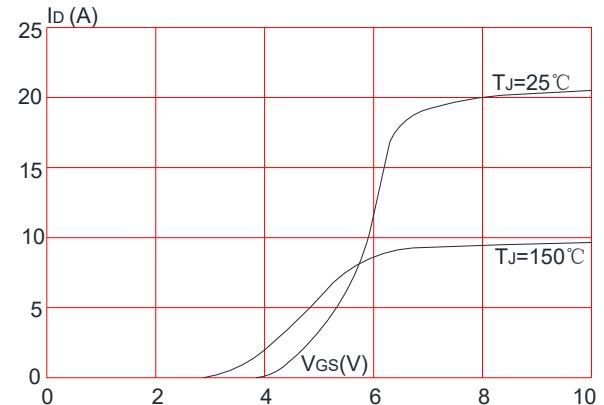


Figure 3: On-resistance vs. Drain Current

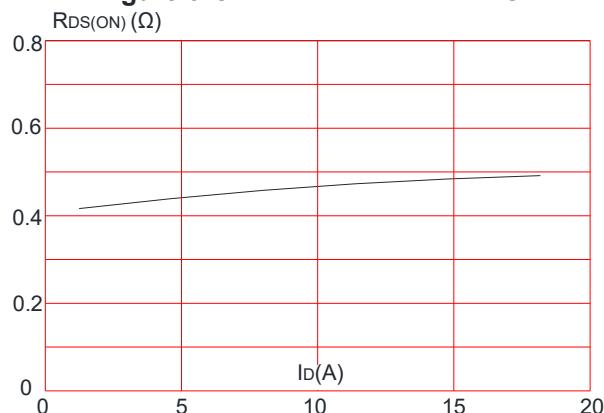


Figure 4: Body Diode Characteristics

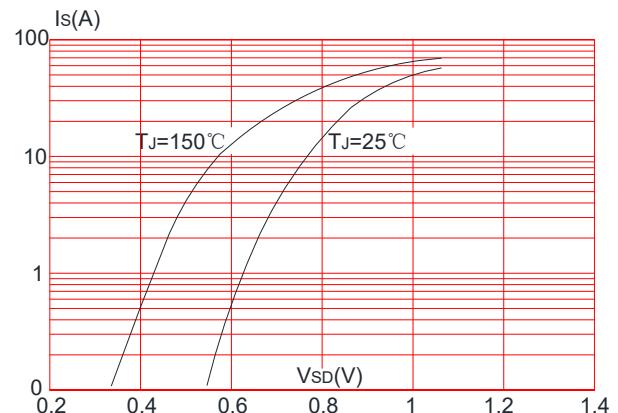


Figure 5: Gate Charge Characteristics

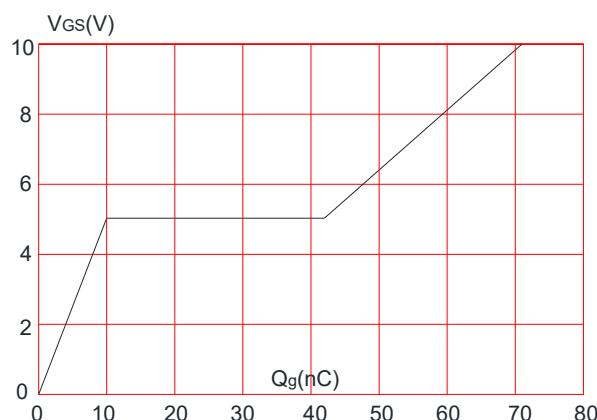
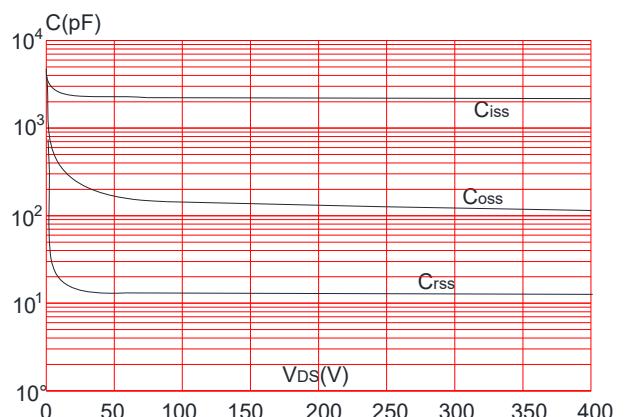


Figure 6: Capacitance Characteristics



TYPICAL PERFORMANCE CHARACTERISTICS(cont.)

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

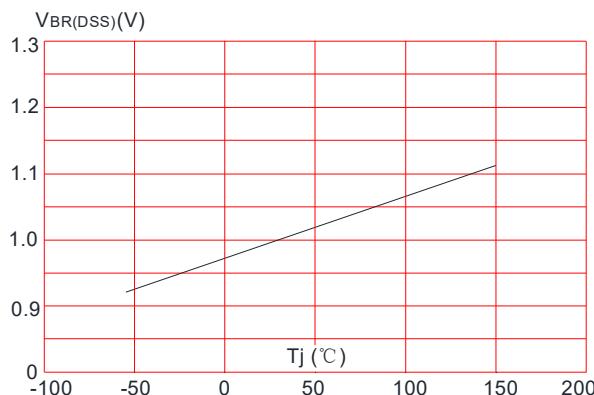


Figure 8: Normalized on Resistance vs. Junction Temperature

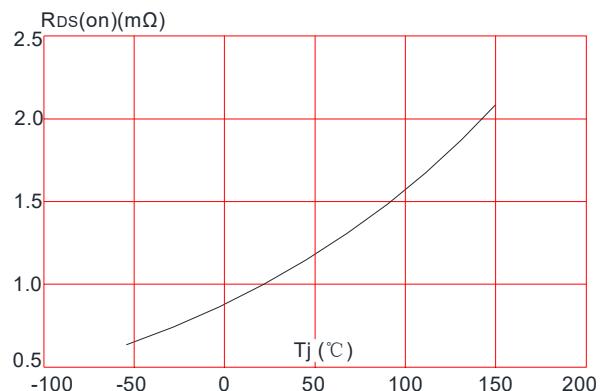


Figure 9: Maximum Safe Operating Area

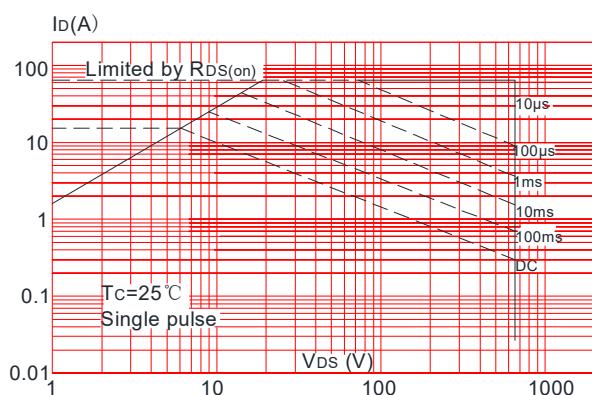


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

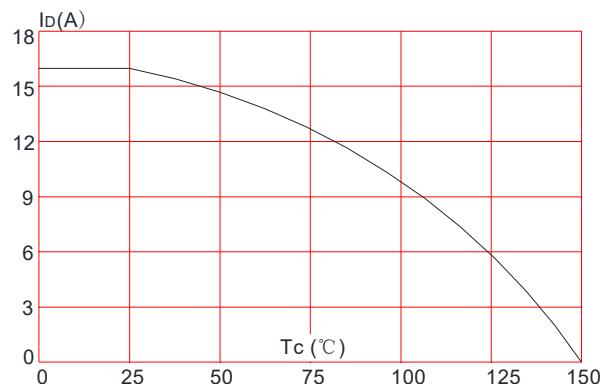
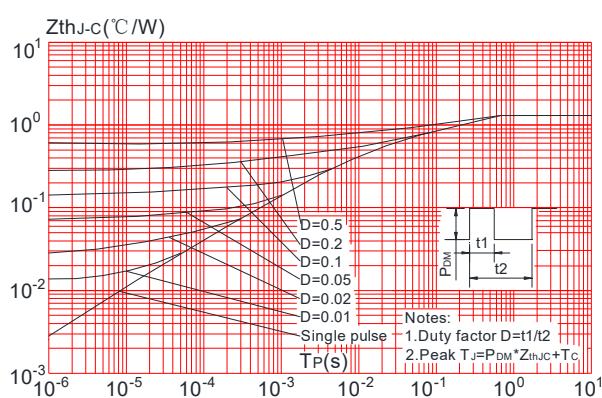
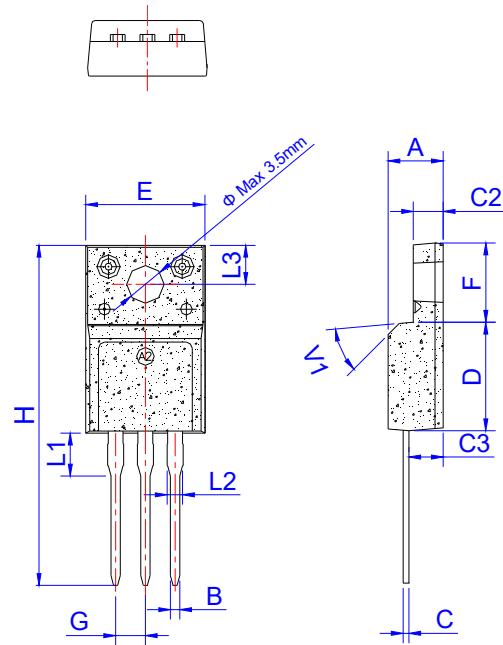


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



TO-220F PACKAGE OUTLINE DRAWING



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.50		4.90	0.177		0.193
B	0.74	0.80	0.83	0.029	0.031	0.033
C	0.47		0.65	0.019		0.026
C2	2.45		2.75	0.096		0.108
C3	2.60		3.00	0.102		0.118
D	8.80		9.30	0.346		0.366
E	9.80		10.4	0.386		0.410
F	6.40		6.80	0.252		0.268
G		2.54			0.1	
H	28.0		29.8	1.102		1.173
L1		3.63			0.143	
L2	1.14		1.70	0.045		0.067
L3		3.30			0.130	
V1		45°			45°	